74AHC1G14-Q100; 74AHCT1G14-Q100

Inverting Schmitt trigger

Rev. 1 — 13 July 2012

Product data sheet

1. General description

74AHC1G14-Q100 and 74AHCT1G14-Q100 are high-speed Si-gate CMOS devices. They provide an inverting buffer function with Schmitt-trigger action. These devices can transform slowly changing input signals into sharply defined, jitter-free output signals.

The AHC device has CMOS input switching levels and supply voltage range 2 V to 5.5 V.

The AHCT device has TTL input switching levels and supply voltage range 4.5 V to 5.5 V.

This product has been qualified to the Automotive Electronics Council (AEC) standard Q100 (Grade 1) and is suitable for use in automotive applications.

2. Features and benefits

- Automotive product qualification in accordance with AEC-Q100 (Grade 1)
 - ◆ Specified from -40 °C to +85 °C and from -40 °C to +125 °C
- Symmetrical output impedance
- High noise immunity
- Low power dissipation
- Balanced propagation delays
- ESD protection:
 - ◆ MIL-STD-883, method 3015 exceeds 2000 V
 - ◆ HBM JESD22-A114F exceeds 2000 V
 - ♦ MM JESD22-A115-A exceeds 200 V (C = 200 pF, R = 0 Ω)
- SOT353-1 and SOT753 package options

3. Applications

- Wave and pulse shapers
- Astable multivibrators
- Monostable multivibrators



Ordering information

Table 1. **Ordering information**

Type number	Package											
	Temperature range	Name	Description	Version								
74AHC1G14GW-Q100	–40 °C to +125 °C	TSSOP5	plastic thin shrink small outline package; 5 leads;	SOT353-1								
74AHCT1G14GW-Q100			body width 1.25 mm									
74AHC1G14GV-Q100	–40 °C to +125 °C	SC-74A	plastic surface-mounted package; 5 leads	SOT753								
74AHCT1G14GV-Q100												

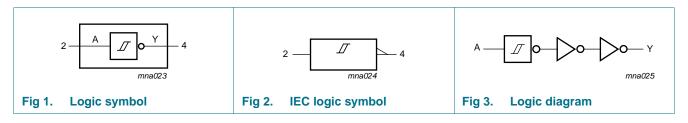
Marking 5.

Table 2. **Marking codes**

Type number	Marking code ^[1]
74AHC1G14GW-Q100	AF
74AHCT1G14GW-Q100	CF
74AHC1G14GV-Q100	A14
74AHCT1G14GV-Q100	C14

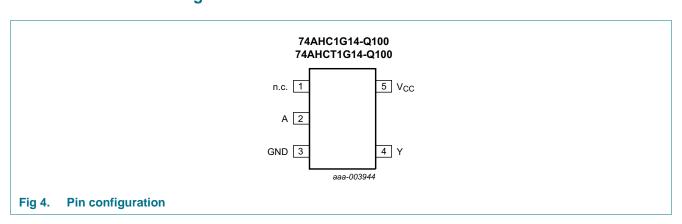
^[1] The pin 1 indicator is on the lower left corner of the device, below the marking code.

Functional diagram 6.



Pinning information 7.

7.1 Pinning



74AHC_AHCT1G14_Q100

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7.2 Pin description

Table 3. Pin description

Symbol	Pin	Description
n.c.	1	not connected
Α	2	data input
GND	3	ground (0 V)
Υ	4	data output
V_{CC}	5	supply voltage

8. Functional description

Table 4. Function table

H = HIGH voltage level; L = LOW voltage level

Input	Output
A	Υ
L	Н
H	L

9. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
V_{CC}	supply voltage		-0.5	+7.0	V
VI	input voltage		-0.5	+7.0	V
I _{IK}	input clamping current	$V_{I} < -0.5 V$	-20	-	mA
I _{OK}	output clamping current	$V_O < -0.5 \text{ V or } V_O > V_{CC} + 0.5 \text{ V}$	<u>[1]</u> -	±20	mA
I _O	output current	$-0.5 \text{ V} < \text{V}_{\text{O}} < \text{V}_{\text{CC}} + 0.5 \text{ V}$	-	±25	mA
I _{CC}	supply current		-	75	mA
I _{GND}	ground current		-75	-	mA
T _{stg}	storage temperature		-65	+150	°C
P _{tot}	total power dissipation	$T_{amb} = -40 ^{\circ}\text{C} \text{ to } +125 ^{\circ}\text{C}$	[2] -	250	mW

^[1] The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

^[2] For both TSSOP5 and SC-74A packages: above 87.5 $^{\circ}$ C the value of P $_{tot}$ derates linearly with 4.0 mW/K.

10. Recommended operating conditions

Table 6. Recommended operating conditions

Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	74AH0	C1G14-Q	100	74AH	Q100	Unit	
			Min	Тур	Max	Min	Тур	Max	
V_{CC}	supply voltage	'	2.0	5.0	5.5	4.5	5.0	5.5	V
VI	input voltage		0	-	5.5	0	-	5.5	V
Vo	output voltage		0	-	V_{CC}	0	-	V_{CC}	V
T _{amb}	ambient temperature		-40	+25	+125	-40	+25	+125	°C

11. Static characteristics

Table 7. Static characteristics

Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions		25 °C		-40 °C	to +85 °C	–40 °C	Unit	
			Min	Тур	Max	Min	Max	Min	Max	
For type	74AHC1G14-C	100								
V _{OH}	HIGH-level	$V_I = V_{T+}$ or V_{T-}								
	output voltage	$I_O = -50 \mu A$; $V_{CC} = 2.0 \text{ V}$	1.9	2.0	-	1.9	-	1.9	-	V
		$I_{O} = -50 \mu A; V_{CC} = 3.0 V$	2.9	3.0	-	2.9	-	2.9	-	V
		$I_{O} = -50 \mu A; V_{CC} = 4.5 V$	4.4	4.5	-	4.4	-	4.4	-	V
		$I_{O} = -4.0 \text{ mA}; V_{CC} = 3.0 \text{ V}$	2.58	-	-	2.48	-	2.40	-	V
		$I_{O} = -8.0 \text{ mA}; V_{CC} = 4.5 \text{ V}$	3.94	-	-	3.8	-	3.70	-	V
V _{OL}	LOW-level	$V_I = V_{T+}$ or V_{T-}								
	output voltage	$I_O = 50 \mu A$; $V_{CC} = 2.0 \text{ V}$	-	0	0.1	-	0.1	-	0.1	V
		$I_O = 50 \mu A; V_{CC} = 3.0 \text{ V}$	-	0	0.1	-	0.1	-	0.1	V
		$I_O = 50 \mu A; V_{CC} = 4.5 V$	-	0	0.1	-	0.1	-	0.1	V
		$I_O = 4.0 \text{ mA}; V_{CC} = 3.0 \text{ V}$	-	-	0.36	-	0.44	-	0.55	V
		$I_O = 8.0 \text{ mA}; V_{CC} = 4.5 \text{ V}$	-	-	0.36	-	0.44	-	0.55	V
I _I	input leakage current	$V_I = 5.5 \text{ V or GND};$ $V_{CC} = 0 \text{ V to 5.5 V}$	-	-	0.1	-	1.0	-	2.0	μΑ
I _{CC}	supply current	$V_I = V_{CC}$ or GND; $I_O = 0$ A; $V_{CC} = 5.5 \text{ V}$	-	-	1.0	-	10	-	40	μА
Cı	input capacitance		-	1.5	10	-	10	-	10	pF
For type	74AHCT1G14-	Q100								
V _{OH}	HIGH-level	$V_{I} = V_{T+} \text{ or } V_{T-}; V_{CC} = 4.5 \text{ V}$								
	output voltage	$I_{O} = -50 \mu A$	4.4	4.5	-	4.4	-	4.4	-	V
		$I_0 = -8.0 \text{ mA}$	3.94	-	-	3.8	-	3.70	-	V
V_{OL}	LOW-level	$V_I = V_{T+}$ or V_{T-} ; $V_{CC} = 4.5 \text{ V}$								
	output voltage	$I_{O} = 50 \mu A$	-	0	0.1	-	0.1	-	0.1	٧
		$I_0 = 8.0 \text{ mA}$	-	-	0.36	-	0.44	-	0.55	٧
l _l	input leakage current	V _I = 5.5 V or GND; V _{CC} = 0 V to 5.5 V	-	-	0.1	-	1.0	-	2.0	μΑ
74AHC_AHCT10	G14_Q100	All information provided	in this docun	nent is subject	ct to legal dis	sclaimers.		© N	IXP B.V. 2012. All rigi	hts rese

Table 7. Static characteristics ...continued Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions		25 °C		-40 °C	to +85 °C	–40 °C t	Unit	
			Min	Тур	Max	Min	Max	Min	Max	
I _{CC}	supply current	$V_I = V_{CC}$ or GND; $I_O = 0$ A; $V_{CC} = 5.5 \text{ V}$	-	-	1.0	-	10	-	40	μΑ
ΔI_{CC}	additional supply current	per input pin; V_I = 3.4 V; other inputs at V_{CC} or GND; I_O = 0 A; V_{CC} = 5.5 V	-	-	1.35	-	1.5	-	1.5	mA
C _I	input capacitance		-	1.5	10	-	10	-	10	pF

11.1 Transfer characteristics

Table 8. Transfer characteristics

At recommended operating conditions; voltages are referenced to GND (ground = 0 V). See Figure 7 and Figure 8.

Symbol	Parameter	Conditions		25 °C		-40 °C	to +85 °C	-40 °C	Unit	
			Min	Тур	Max	Min	Max	Min	Max	
For type	74AHC1G14-Q1	00	,	'	,		"	•	•	
V_{T+}	positive-going	$V_{CC} = 3.0 \text{ V}$	-	-	2.2	-	2.2	-	2.2	V
	threshold voltage	V _{CC} = 4.5 V	-	-	3.15	-	3.15	-	3.15	V
		V _{CC} = 5.5 V	-	-	3.85	-	3.85	-	3.85	V
V_{T-}	negative-going threshold voltage	$V_{CC} = 3.0 \text{ V}$	0.9	-	-	0.9	-	0.9	-	V
		$V_{CC} = 4.5 \text{ V}$	1.35	-	-	1.35	-	1.35	-	V
		$V_{CC} = 5.5 \text{ V}$	1.65	-	-	1.65	-	1.65	-	V
V_{H}	hysteresis voltage	$V_{CC} = 3.0 \text{ V}$	0.3	-	1.2	0.3	1.2	0.25	1.2	V
		$V_{CC} = 4.5 \text{ V}$	0.4	-	1.4	0.4	1.4	0.35	1.4	V
		$V_{CC} = 5.5 \text{ V}$	0.5	-	1.6	0.5	1.6	0.45	1.6	V
For type	74AHCT1G14-C	1100								
V_{T+}	positive-going	$V_{CC} = 4.5 \text{ V}$	-	-	2.0	-	2.0	-	2.0	V
	threshold voltage	V _{CC} = 5.5 V	-	-	2.0	-	2.0	-	2.0	V
V_{T-}	negative-going	$V_{CC} = 4.5 \text{ V}$	0.5	-	-	0.5	-	0.5	-	V
	threshold voltage	V _{CC} = 5.5 V	0.6	-	-	0.6	-	0.6	-	V
V_{H}	hysteresis	$V_{CC} = 4.5 \text{ V}$	0.4	-	1.4	0.4	1.4	0.35	1.4	V
	voltage	V _{CC} = 5.5 V	0.4	-	1.6	0.4	1.6	0.35	1.6	V

12. Dynamic characteristics

Table 9. Dynamic characteristics

GND = 0 V; $t_f = t_f \le 3.0$ ns. For waveform see <u>Figure 5</u>. For test circuit see <u>Figure 6</u>.

Symbol	Parameter	Conditions			25 °C		-40 °C	to +85 °C	-40 °C	to +125 °C	Unit
						Max	Min	Max	Min	Max	
For type	74AHC1G14	-Q100								•	
t _{pd}	propagation	A to Y;	<u>[1]</u>								
	delay	$V_{CC} = 3.0 \text{ V to } 3.6 \text{ V}$	[2]								
		$C_{L} = 15 pF$		-	4.2	12.8	1.0	15.0	1.0	16.5	ns
		$C_L = 50 pF$		-	6.0	16.3	1.0	18.5	1.0	20.5	ns
		$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$	[3]								
		$C_{L} = 15 pF$		-	3.2	8.6	1.0	10.0	1.0	11.0	ns
		$C_L = 50 pF$		-	4.6	10.6	1.0	12.0	1.0	13.5	ns
C _{PD}	power dissipation capacitance	per buffer; $C_L = 50 \text{ pF}$; $f = 1 \text{ MHz}$; $V_I = \text{GND to } V_{CC}$	[4]	-	12	-	-	-	-	-	pF
For type	74AHCT1G1	4-Q100									
t _{pd}	propagation delay	A to Y; V _{CC} = 4.5 V to 5.5 V	[1] [3]								
		$C_L = 15 pF$		-	4.1	7.0	1.0	8.0	1.0	9.0	ns
		$C_L = 50 pF$		-	5.9	8.5	1.0	10.0	1.0	11.0	ns
C _{PD}	power dissipation capacitance	per buffer; $V_I = GND \text{ to } V_{CC}$	[4]	-	13	-	-	-	-	-	pF

^[1] t_{pd} is the same as t_{PLH} and t_{PHL} .

 $P_D = C_{PD} \times V_{CC}^2 \times f_i + \sum (C_L \times V_{CC}^2 \times f_o)$ where:

 f_i = input frequency in MHz;

 $f_o = output frequency in MHz;$

C_L = output load capacitance in pF;

 V_{CC} = supply voltage in Volts.

^[2] Typical values are measured at $V_{CC} = 3.3 \text{ V}$.

^[3] Typical values are measured at $V_{CC} = 5.0 \text{ V}$.

^[4] C_{PD} is used to determine the dynamic power dissipation P_D (μW).

13. Waveforms

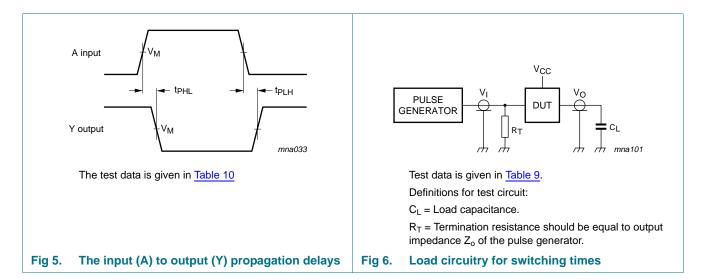
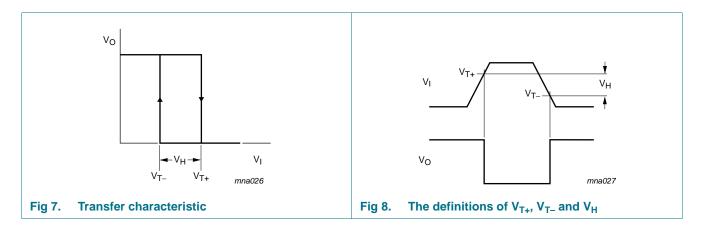


Table 10. Test data

Type number	Input		Output
	V _I	V _M	V _M
74AHC1G14-Q100	GND to V _{CC}	$0.5 \times V_{CC}$	$0.5 \times V_{CC}$
74AHCT1G14-Q100	GND to 3.0 V	1.5 V	$0.5 \times V_{CC}$

13.1 Transfer characteristic waveforms



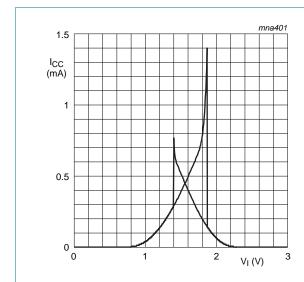


Fig 9. Typical 74AHC1G14-Q100 transfer characteristics; V_{CC} = 3.0 V

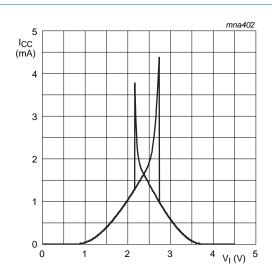


Fig 10. Typical 74AHC1G14-Q100 transfer characteristics; V_{CC} = 4.5 V

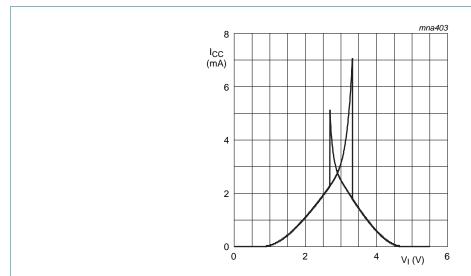
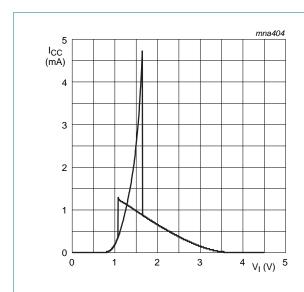


Fig 11. Typical 74AHC1G14-Q100 transfer characteristics; $V_{CC} = 5.5 \text{ V}$





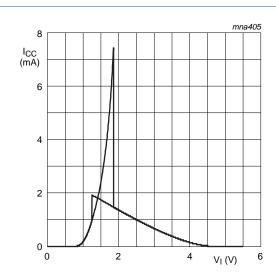


Fig 13. Typical 74AHCT1G14-Q100 transfer characteristics; $V_{CC} = 5.5 \text{ V}$

14. Application information

The slow input rise and fall times cause additional power dissipation, which can be calculated using the following formula:

 $P_{add} = f_i \times (t_r \times \Delta I_{CC(AV)} + t_f \times \Delta I_{CC(AV)}) \times V_{CC}$ where:

 P_{add} = additional power dissipation (μW);

 $f_i = input frequency (MHz);$

 t_r = input rise time (ns); 10 % to 90 %;

 t_f = input fall time (ns); 90 % to 10 %;

 $\Delta I_{CC(AV)}$ = average additional supply current (μA).

Average additional I_{CC} differs with positive or negative input transitions, as shown in Figure 14 and Figure 15.

For 74AHC1G14-Q100 and 74AHCT1G14-Q100 used in relaxation oscillator circuit, see Figure 16.

Note to the application information:

1. All values given are typical unless otherwise specified.

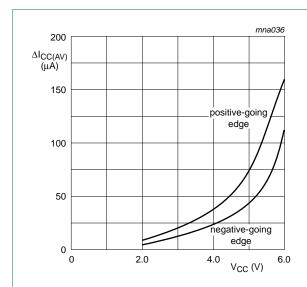


Fig 14. Average additional I_{CC} for 74AHC1G14-Q100 Schmitt-trigger devices; linear change of V_I between 0.1V_{CC} to 0.9V_{CC}

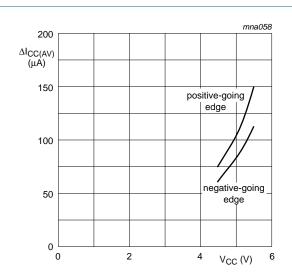
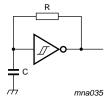


Fig 15. Average additional I_{CC} for 74AHCT1G14-Q100 Schmitt-trigger devices; linear change of V_I between $0.1V_{CC}$ to $0.9V_{CC}$



For 74AHC1G14-Q100: $f = \frac{1}{T} \approx \frac{1}{0.55 \times RC}$

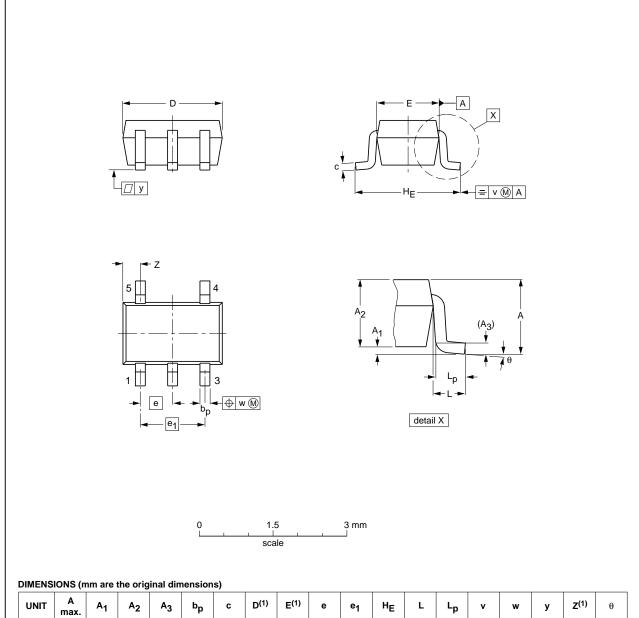
For 74AHCT1G14-Q100: $f = \frac{1}{T} \approx \frac{1}{0.60 \times RC}$

Fig 16. Relaxation oscillator using the 74AHC1G14-Q100 and 74AHCT1G14-Q100

15. Package outline

TSSOP5: plastic thin shrink small outline package; 5 leads; body width 1.25 mm

SOT353-1



UN	TIN	A max.	A ₁	A ₂	A ₃	bp	С	D ⁽¹⁾	E ⁽¹⁾	е	e ₁	HE	L	Lp	v	w	у	Z ⁽¹⁾	θ
m	ım	1.1	0.1 0	1.0 0.8	0.15	0.30 0.15	0.25 0.08	2.25 1.85	1.35 1.15	0.65	1.3	2.25 2.0	0.425	0.46 0.21	0.3	0.1	0.1	0.60 0.15	7° 0°

Note

1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.

OUTLINE	REFERENCES				EUROPEAN	ISSUE DATE
VERSION	IEC	JEDEC	JEITA		PROJECTION	ISSUE DATE
SOT353-1		MO-203	SC-88A			-00-09-01 03-02-19

Fig 17. Package outline SOT353-1 (TSSOP5)

74AHC_AHCT1G14_Q100

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Plastic surface-mounted package; 5 leads

SOT753

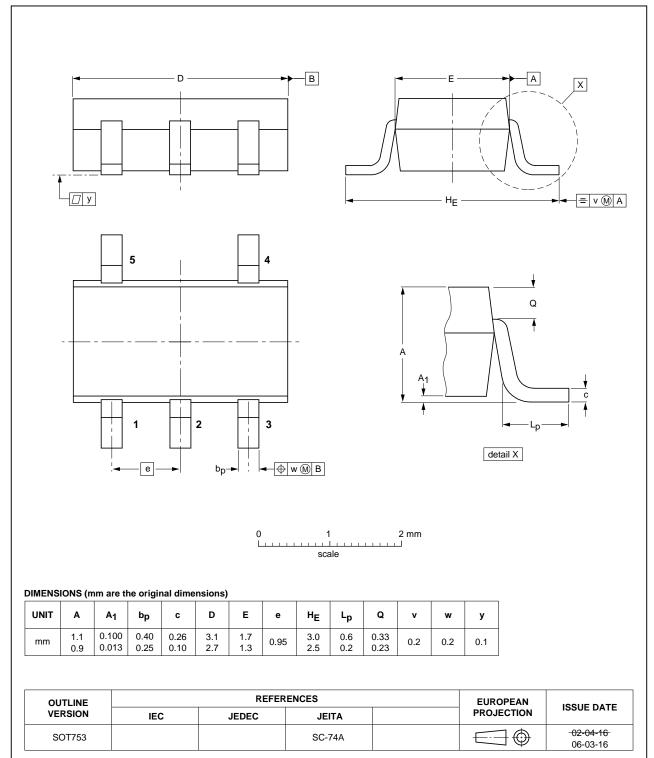


Fig 18. Package outline SOT753 (SC-74A)

74AHC_AHCT1G14_Q100

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16. Abbreviations

Table 11. Abbreviations

Acronym	Description
CDM	Charged Device Model
CMOS	Complementary Metal-Oxide Semiconductor
DUT	Device Under Test
ESD	ElectroStatic Discharge
HBM	Human Body Model
MM	Machine Model
TTL	Transistor-Transistor Logic
MIL	Military

17. Revision history

Table 12. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
74AHC_AHCT1G14_Q100 v.1	20120713	Product data sheet	-	-

18. Legal information

18.1 Data sheet status

Document status[1][2]	Product status[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

- [1] Please consult the most recently issued document before initiating or completing a design.
- [2] The term 'short data sheet' is explained in section "Definitions"
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